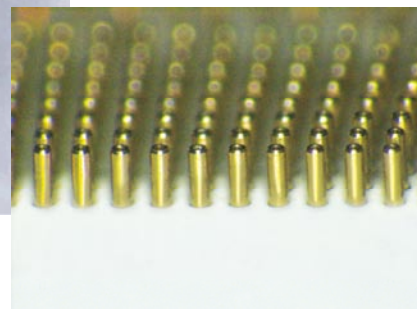
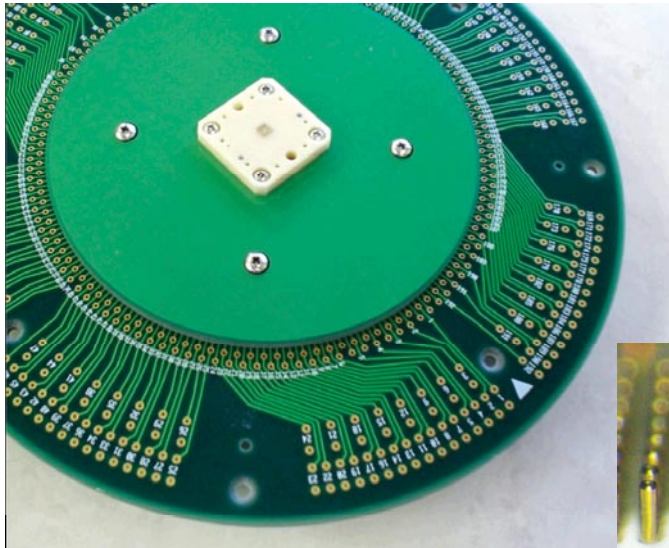


Yokowo Vertical Probe Card (YVP series)



Yokowo Vertical Probe Card

Applications

- Solder bump and gold plating pad / Aluminum pad probing
- Wafer Level Package Single/Multi DUT probing
- Flip Chip probing

Features

- Free to define probing layout (peripherals/matrix) due to vertical contact technology.
- Contact probe is replaceable by a tweezers easily.
- Double-ended contact probe absorbs mechanical stress and prevents damage for the receptacle and wires.
- Light tuned spring force helps to reduce a risk of damage for bumps and pads.
- Original Crown type plunger exclusively developed for a solder bump assures consistent contact resistance and long life cycles time.

Specifications

Minimum pitch	120μm	150μm	200μm	280μm	380μm
Outer diameter	96μm	110μm	150μm	200μm	300μm
Spring force (OD : 100μm)	4.5g	4.5g	5.5g	5.5g	5.5g
Electrical current	0.17A	0.24A	0.3A	0.4A	0.5A
Tip style	Crown for bump and cone for pad				
Plunger material	Gold alloy / pd alloy				
Pointing accuracy	± 15μm				
Planarity	20μm				
Maximum temperature	125°C				